

CHALLENGE: High pin count, high clock speed, thermal requirement and power consumption constraints required radically new packaging and interconnect method for Pentium chips. Existing processes and equipment were obsolete.

SOLUTION:

- Principal's company (AMTI) engaged with **Intel** Advanced Manufacturing in a strategic partnership
- Intel engineers and scientists along with AMTI engineers developed very ambitious new processes and associated automation equipment to implement multi-chip module assembly process for “flip-chip”.
- AMTI deliverable consisted of 8-10 distinct automated machines per assembly line.
- Development project lasted 2+ years. Resulted in successful replication and deployment of assembly lines in Intel global assembly plants over next 4 years.
- Intel/AMTI collaboration on Pentium recognized as one of Intel's most successful new product launches in it's history.
- Principal was key person in strategy and negotiation of AMTI sale to Swiss multinational